Special Issue

Future Information & Communication Engineering 2025

Message from the Guest Editors

This Special Issue will comprise selected papers from The 17th International Conference on Future Information & Communication Engineering (ICFICE 2025), which was held at the Hotel Nikko Guam, USA on 1st–4th July 2025. Following ICFICE 2025, we will organize a Special Issue, soliciting original research papers on all of the technical aspects of computer science, information, and communication engineering. Potential topics include, but are not limited to, the following:

- Communication systems and applications;
- Networking and services;
- Al and intelligent information systems;
- Multimedia and digital convergence;
- Semiconductor and communication services;
- Biomedical imaging and engineering;
- Ubiquitous sensor networks;
- Database and internet applications;
- IoT and Big Data:
- IT convergence technology.

Guest Editors

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Prof. Dr. Daesung Lee

Dr. Jun-Ho Huh

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Deadline for manuscript submissions

30 June 2026



Applied Sciences

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Impact Factor 2.5 CiteScore 5.5



mdpi.com/si/253534

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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